

AB L1&L2 v1.1.4 - 0.5mm, 5-layer Board with Microvias

Material Selection

Halogen-free FR-4
Permittivity @ 100MHz:
Permittivity @ 1GHz:
Loss Tangent @ 100MHz:
Loss Tangent @ 1GHz:
Lead Free Assembly Compatible

Solder resist colour: green
Silkscreen print colour: white

Surface Finish

On top and bottom layer surfaces:
electroless nickel immersion gold

Non-standard Tolerances

Holes sized 0.2mm may be plugged by plating. These are all vias.
For them we do not care the finished hole sizes.

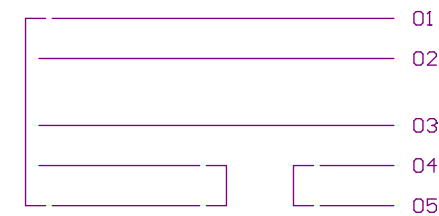
Board Layer Stack

Cu 18um*	Prepreg VT47-1080 60um	01	_____
Cu 35um	Core VT47 76um	02	_____
Cu 35um	Prepreg VT47-1080 60um	03	_____
Cu 35um	Core VT47 76um	04	_____
Cu 18um*	Prepreg VT47-1080 60um	05	_____

*35um final after plating

Total Laminated Thickness: 0.5mm +/- 0.05mm !

Drill Layer-Pairs



Layer Name Gerber

Top Overlay	.gto
Top Solder Mask	.gts
Top Layer	.gtl
Plane 1 (GND)	.gp1
Mid Layer 1	.gl
Plane 2 (GND)	.gp2
Bottom Layer	.gbl
Bottom Solder Mask	.gbs
Bottom Overlay	.gbo
Bottom Paste Mask	.gpb
Board Outline	.gm1

Holes / Drilling

Drill files contain finished hole diameters
Drilling layer pairs: 4-5, 1-5

Board Outline

Contour routed with break-away tabs

Element Counts

(for reference only)

Components: 36
Nets: 79
Pads: 351
Tracks: 1671
Polygons: 19
Holes: 241
Vias: 214

Controlled Impedance Reference

Diff. trace width/space on bottom layer (microstrip) 75 ohms D10% : 0.125/0.1mm

Diff. trace width/space on top and bottom layer (microstrip) 60 ohms D10% : 0.175/0.1mm